



0805L Series



Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E183209
	R50119118

Description

The 0805L Series PTC provides surface mount overcurrent protection for applications where space is at a premium and resettable protection is desired.



Features

- RoHS compliant, lead-free and halogen-free
- Fast response to fault currents
- Compact design saves board space
- Low resistance
- Low-profile
- Compatible with high temperature solders

Applications

- USB peripherals
- Disk drives
- CD-ROMs
- Plug and play protection for motherboards and peripherals
- Mobile phones - battery and port protection
- Disk drives
- PDAs / digital cameras
- Game console port protection

Electrical Characteristics

Part Number	Marking	I_{hold} (A)	I_{trip} (A)	V_{max} (Vdc)	I_{max} (A)	P_d typ. (W)	Maximum Time To Trip		Resistance		Agency Approvals	
							Current (A)	Time (Sec.)	R_{min} (Ω)	R_{1max} (Ω)		
0805L010	A	0.10	0.30	15	100	0.5	0.50	1.50	1.000	6.000	X	X
0805L010/24	J	0.10	0.30	24	100	0.5	0.50	1.50	1.500	6.000	X	X
0805L020	C	0.20	0.50	9	100	0.5	8.00	0.02	0.650	3.500	X	X
0805L035	E	0.35	0.75	6	100	0.5	8.00	0.10	0.250	1.200	X	X
0805L050 ¹	F	0.50	1.00	6	100	0.5	8.00	0.10	0.150	0.850	X	X
0805L075	G	0.75	1.50	6	40	0.6	8.00	0.20	0.090	0.350	X	X
0805L100	N	1.00	1.95	6	40	0.6	8.00	0.30	0.060	0.210	X	X
0805L110	H	1.10	2.00	6	100	0.8	8.00	0.10	0.050	0.160	X	X

I_{hold} = Hold current: maximum current device will pass without tripping in 20°C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 20°C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

P_d = Power dissipated from device when in the tripped state at 20°C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{typ} = Typical resistance of device in initial (un-soldered) state.

R_{1max} = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

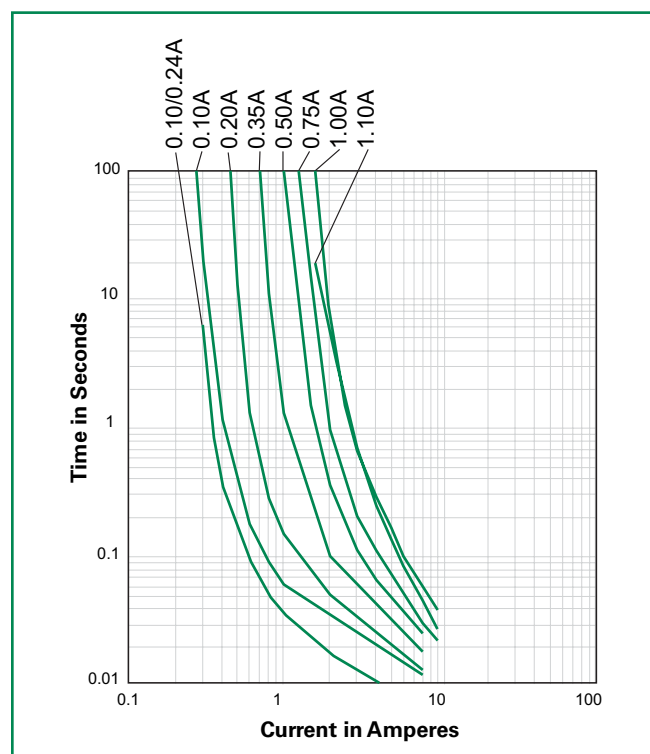
¹ Part Number tested and complied with AEC-Q200.

Temperature Derating

Part Number	Ambient Operation Temperature								
	-40°C	-20°C	0°C	20°C	40°C	50°C	60°C	70°C	85°C
Hold Current (A)									
0805L010	0.14	0.12	0.11	0.10	0.08	0.07	0.06	0.05	0.03
0805L010/24	0.15	0.13	0.12	0.10	0.09	0.08	0.07	0.06	0.04
0805L020	0.28	0.25	0.23	0.20	0.17	0.14	0.12	0.10	0.07
0805L035	0.47	0.44	0.39	0.35	0.30	0.27	0.24	0.20	0.14
0805L050	0.68	0.62	0.55	0.50	0.40	0.37	0.33	0.29	0.23
0805L075	1.00	0.90	0.79	0.75	0.63	0.57	0.53	0.41	0.34
0805L100	1.35	1.25	1.10	1.00	0.82	0.74	0.65	0.55	0.42
0805L110	1.45	1.35	1.20	1.10	0.92	0.84	0.75	0.65	0.52

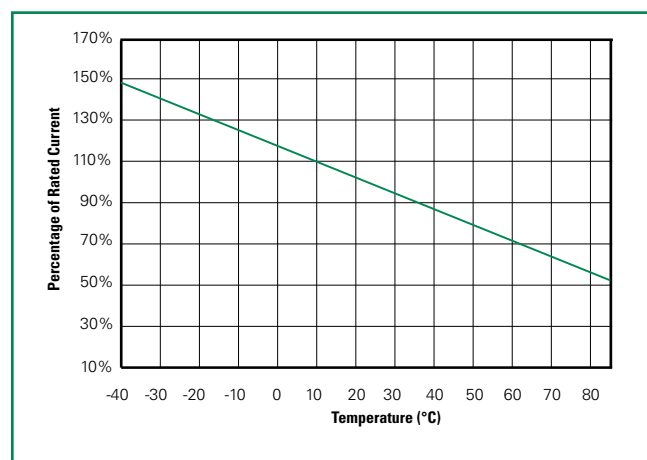
Notes: The temperature derating data is only for reference, please contact Littelfuse technical support for detail temperature derating information.

Average Time Current Curves



The average time current curves and Temperature Derating curve performance is affected by a number of variables, and these curves provided as guidance only. Customer must verify the performance in their application.

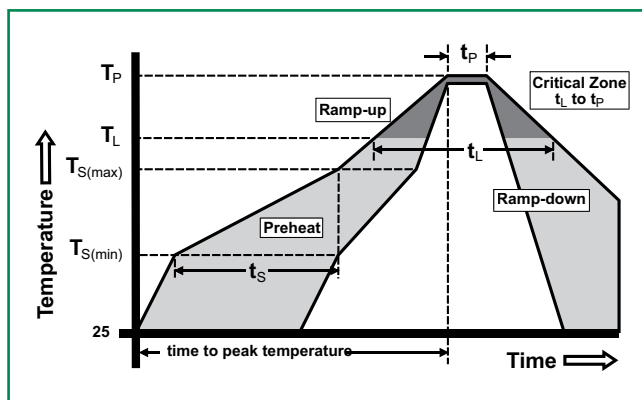
Temperature Derating Curve



Note:
Typical Temperature derating curve, refer to table for derating data

Soldering Parameters

Profile Feature		Pb-Free Assembly
Average Ramp-Up Rate ($T_{S(max)}$ to T_P)		3°C/second max
Pre Heat:	Temperature Min ($T_{S(min)}$)	150°C
	Temperature Max ($T_{S(max)}$)	200°C
	Time (Min to Max) (t_s)	60 – 180 secs
Time Maintained Above:	Temperature (T_L)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak / Classification Temperature (T_P)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.



- All temperature refer to topside of the package, measured on the package body surface
- If reflow temperature exceeds the recommended profile, devices may not meet the performance requirements
- Recommended reflow methods: IR, vapor phase oven, hot air oven, N_2 environment for lead
- Recommended maximum paste thickness is 0.25mm (0.010inch)
- Devices can be cleaned using standard industry methods and solvents
- Devices can be reworked using the standard industry practices

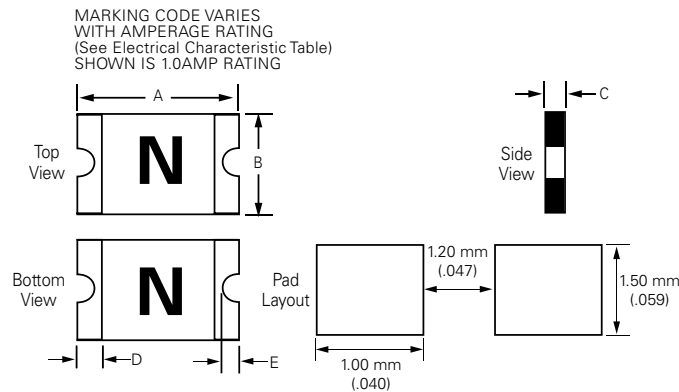
Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material: Matte Tin (Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002, Category 3

Environmental Specifications

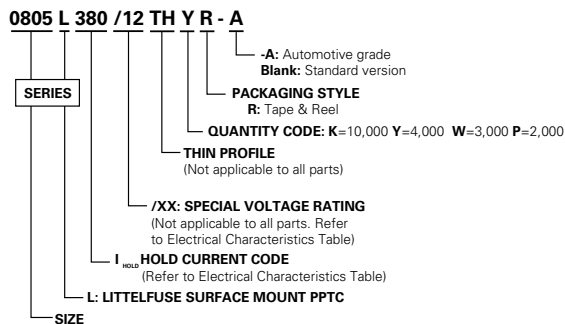
Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours -/±5% typical resistance change
Humidity Aging	+85°C, 85%, R.H., 1000 hours -/±5% typical resistance change
Thermal Shock	MIL-STD-202, Method 107 +85°C/-40°C 20 times -30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 No change
Vibration	MIL-STD-883, Method 2007, Condition A No change
Moisture Sensitivity Level	Level 1, J-STD-020

Dimensions



Part Number	A				B				C				D				E			
	Inches		mm		Inches		mm		Inches		mm		Inches		mm		Inches		mm	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
0805L010	0.08	0.09	2.00	2.20	0.05	0.06	1.20	1.50	0.02	0.04	0.55	1.00	0.01	0.02	0.20	0.55	0.002	0.02	0.05	0.45
0805L010/24	0.08	0.09	2.00	2.20	0.05	0.06	1.20	1.50	0.02	0.04	0.55	1.00	0.01	0.02	0.20	0.55	0.002	0.02	0.05	0.45
0805L020	0.08	0.09	2.00	2.20	0.05	0.06	1.20	1.50	0.02	0.04	0.55	1.00	0.01	0.02	0.20	0.55	0.002	0.02	0.05	0.45
0805L035	0.08	0.09	2.00	2.20	0.05	0.06	1.20	1.50	0.02	0.03	0.45	0.75	0.01	0.02	0.20	0.55	0.002	0.02	0.05	0.45
0805L050	0.08	0.09	2.00	2.20	0.05	0.06	1.20	1.50	0.03	0.05	0.75	1.25	0.01	0.02	0.20	0.55	0.002	0.02	0.05	0.45
0805L075	0.08	0.09	2.00	2.20	0.05	0.06	1.20	1.50	0.03	0.05	0.75	1.25	0.01	0.02	0.20	0.55	0.002	0.02	0.05	0.45
0805L100	0.08	0.09	2.00	2.20	0.05	0.06	1.20	1.50	0.02	0.07	0.50	1.80	0.01	0.02	0.20	0.55	0.002	0.02	0.05	0.45
0805L110	0.08	0.09	2.00	2.20	0.05	0.06	1.20	1.50	0.03	0.06	0.80	1.40	0.01	0.02	0.20	0.55	0.002	0.02	0.05	0.45

Part Ordering Number System



Packaging

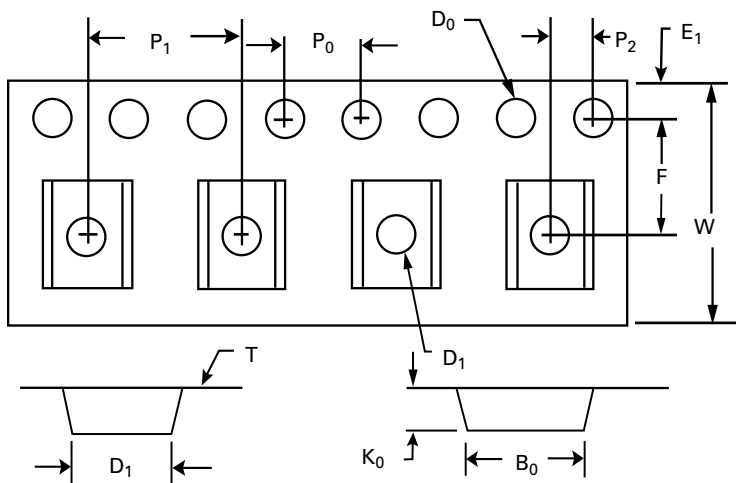
Part Number	Ordering Number	Halogen Free	I_{hold} (A)	I_{hold} Code	Packaging Option	Quantity	Quantity & Packaging Codes
0805L010	0805L010YR	Yes	0.10	010	Tape and Reel	4000	YR
0805L010/24	0805L010/24YR	Yes	0.10	010	Tape and Reel	4,000	YR
0805L020	0805L020YR	Yes	0.20	020	Tape and Reel	4000	YR
0805L035	0805L035YR	Yes	0.35	035	Tape and Reel	4000	YR
0805L050	0805L050WR	Yes	0.50	050	Tape and Reel	3000	WR
0805L075	0805L075WR	Yes	0.75	075	Tape and Reel	3000	WR
0805L100	0805L100WR	Yes	1.00	100	Tape and Reel	3000	WR
0805L110	0805L110WR	Yes	1.10	110	Tape and Reel	3000	WR

Tape and Reel Specifications

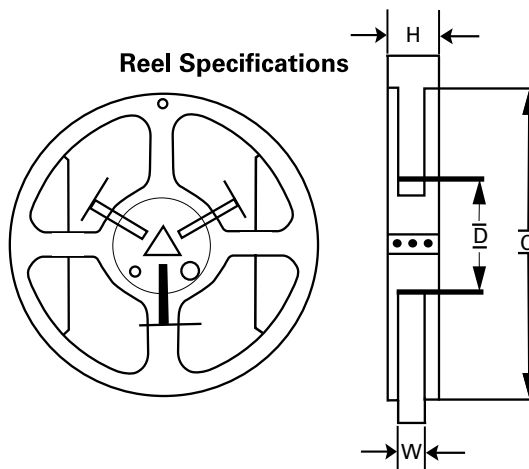
TAPE SPECIFICATIONS: EIA-481-1 (mm)			
	0805L010 0805L020 0805L035 0805L010/24	0805L050 0805L075 0805L100	0805L110
W	8.00+/-0.10	8.00+/-0.30	8.00+/-0.30
F	3.50+/-0.05	3.50+/-0.05	3.50+/-0.05
E₁	1.75+/-0.10	1.75+/-0.10	1.75+/-0.10
D₀	1.55+/-0.05	1.55+/-0.05	1.55+/-0.05
D₁	1.00 (min)	1.00+/-0.10	1.00+/-0.10
P₀	4.00+/-0.10	4.00+/-0.10	4.00+/-0.10
P₁	4.00+/-0.10	4.00+/-0.10	4.00+/-0.10
P₂	2.00+/-0.05	2.00+/-0.05	2.00+/-0.05
A₀	1.45+/-0.10	1.65+/-0.10	1.65+/-0.10
B₀	2.30+/-0.10	2.35+/-0.10	2.35+/-0.10
T	0.25+/-0.10	0.20+/-0.10	0.25+/-0.10
K₀	0.90+/-0.10	1.05+/-0.10	1.50+/-0.10
<i>Leader min.</i>	390	390	390
<i>Trailer min.</i>	160	160	160

REEL DIMENSIONS: EIA-481-1 (mm)	
C	Ø178+/-1.0
D	Ø60.2+0.5
H	11.0+/-0.5
W	9.0+/-1.5

Tape Specifications



Reel Specifications



WARNING

- Users shall independently assess the suitability of these devices for each of their applications
- Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire
- These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the performance of these PPTC devices
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses
- Circuits with inductance may generate a voltage ($L \cdot di/dt$) above the rated voltage of the PPTC device.